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Bulletin

We hereby certify that the resins below produced by CHIMEI CORPORATION

POLYLAC® ABS PA-763, PA-763A, PA-764, PA-764B, PA-764G

conforms to the requirement that no chemicals as following are intentionally added.

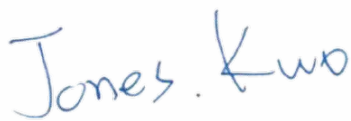
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| 1. PBDEs (Polybrominated Diphenyl Ethers) | 35. Perchlorate |
| 2. PBBs (Polybrominated Biphenyls) | 36. Hexachlorobenzene |
| 3. Ozone Depleting Chemicals (CFCs & HCFCs) | 37. Mirex |
| 4. Chlorinated Paraffin (C10-C13) | 38. Specified amine compounds |
| 5. Polyvinyl Chloride (PVC) | 39. Benzene |
| 6. Mercury (Hg) and its compounds | 40. Benzenamine, <i>N</i> -phenyl-, Reaction Products with Styrene and 2,4,4-Trimethylpentene (BNST) |
| 7. Lead (Pb) and its compounds | 41. Polyamide |
| 8. Cadmium (Cd) and its compounds | 42. PVDC (polyvinylidene chloride) |
| 9. Chromium (Cr) and its compounds | 43. ESBO (Expoxidized soybean oil) |
| 10. Arsenic (As) and its compounds | 44. Formamide |
| 11. Selenium (Se) and its compounds | 45. Hexabromocyclododecane (HBCDD) |
| 12. Barium (Ba) and its compounds | 46. Red phosphorus |
| 13. Beryllium (Be) and its compounds | 47. Aniline · formaldehyde polycondensate |
| 14. Bismuth (Bi) and its compounds | 48. Fluorescent powder |
| 15. Organic tin compounds (TBT, TPT, DOT, DBT) | 49. 4,4'-Sulfonyldiphenol (BPS) |
| 16. Polychlorinated Biphenyls (PCBs) and Terphenyls (PCTs) and Naphtalenes (PCNs) | 50. Tris (2-chloro-1-methylethyl) phosphate (TCPP) |
| 17. Poly naphthalenes | 51. Tris (1,3-Dichloro-2-propyl) phosphate (TDCPP) |
| 18. Azo colorants (according to REACH-ANNEX-XVII-APPENDIX 8) | 52. Tris (2,3-dibromopropyl) phosphate |
| 19. Asbestos | 53. Tris (aziridiny) phosphin oxide |
| 20. Phthalates | 54. Tri- <i>o</i> -cresyl phosphate |
| 21. APEO: Including Alkylphenol(AP), Octylphenol(OP), Nonylphenol(NP), Octylphenol ethoxylates(OPE), Nonylphenol ethoxylates(NPE) | 55. Tris (2-chloroethyl) phosphate (TCEP) |
| 22. 2-(2'-Hydroxy-3',5'-di-tert-butylphenyl)benzotriazole | 56. Perfluorohexane-1-sulphonic acid and its salts (PFHxS) |
| 23. PFOA, PFOS, PFAS | 57. Diisononyl phthalate (DINP) |
| 24. Bisphenol A | 58. Di-isodecyl phthalate (DIDP) |
| | 59. Di- <i>n</i> -octyl phthalate (DnOP) |
| | 60. Diethyl phthalate (DEP) |
| | 61. Dimethyl phthalate (DMP) |
| | 62. Cobalt |
| | 63. Mica |

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| 25. Formaldehyde | 64. Graphite |
| 26. Dimethylfumarate (DMF) | 65. Bis (2-ethylhexyl) phthalate (DEHP) |
| 27. Triclosan | 66. Butyl benzyl phthalate (BBP) |
| 28. Nickel | 67. Dibutyl phthalate (DBP) |
| 29. PAHs (Polycyclic Aromatic Hydrocarbons) | 68. Diisobutyl phthalate (DIBP) |
| 30. REACH- Candidate List of 235 SVHCs(2023/06/14) | 69. PIP (3:1) (phenol, isopropylated phosphate 3:1) |
| 31. Radioactive Substances | 70. DecaBDE (decabromodiphenyl ether) |
| 32. Natural Latex | 71. 2,4,6-TTBP (2,4,6-Tris(tert-butyl)phenol) |
| 33. Dioxins and furans | 72. HCBd (hexachlorobutadiene) |
| 34. Primary aromatic amines (PAA) | 73. PCTP (pentachlorothiophenol) |

With regard to composition of above grades of products, the aforesaid products comply with the Directives of RoHS 2011/65/EU and its amendment (EU) 2015/863

Sincerely Yours,



Jones Kuo

Vice President of Research and Development Head Division

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